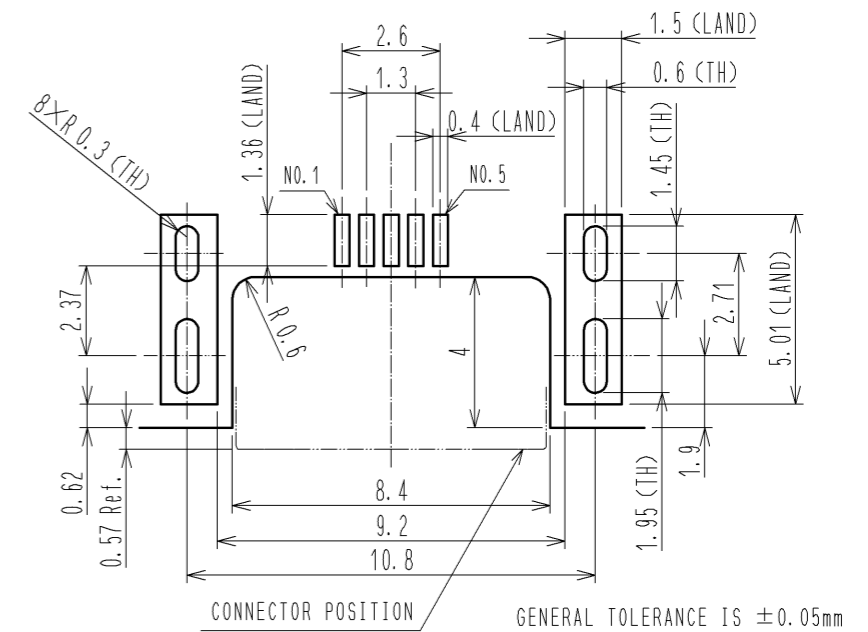


PCB BOARD PATTERN FOR REFERENCE(FREE)

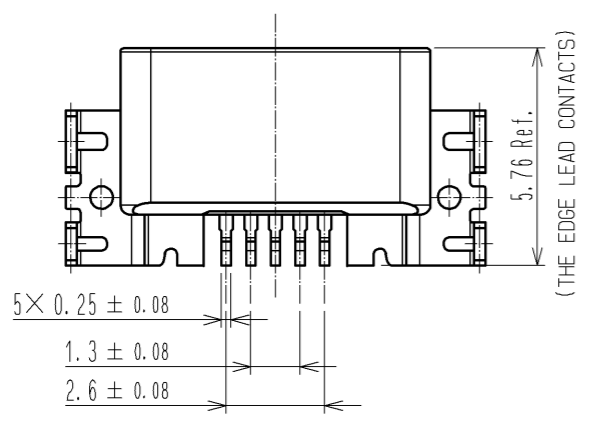
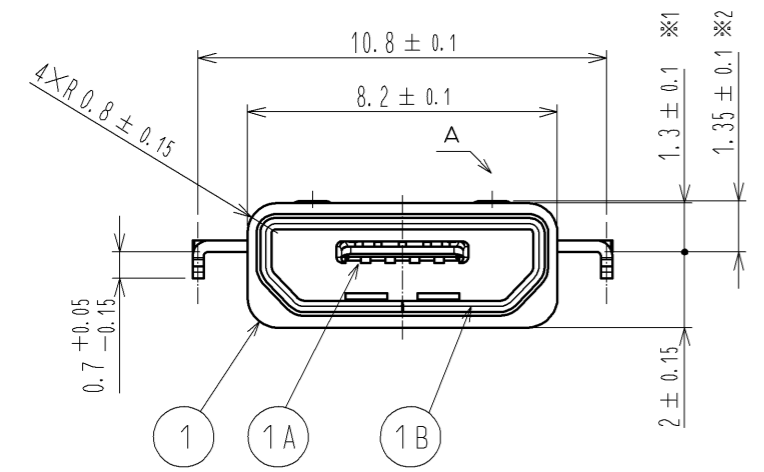
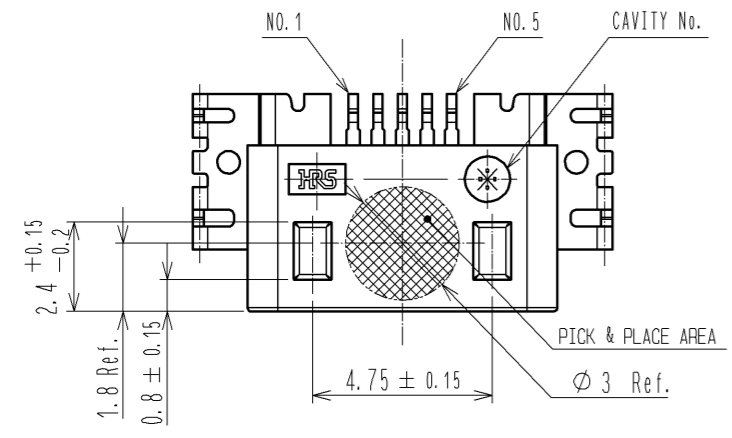
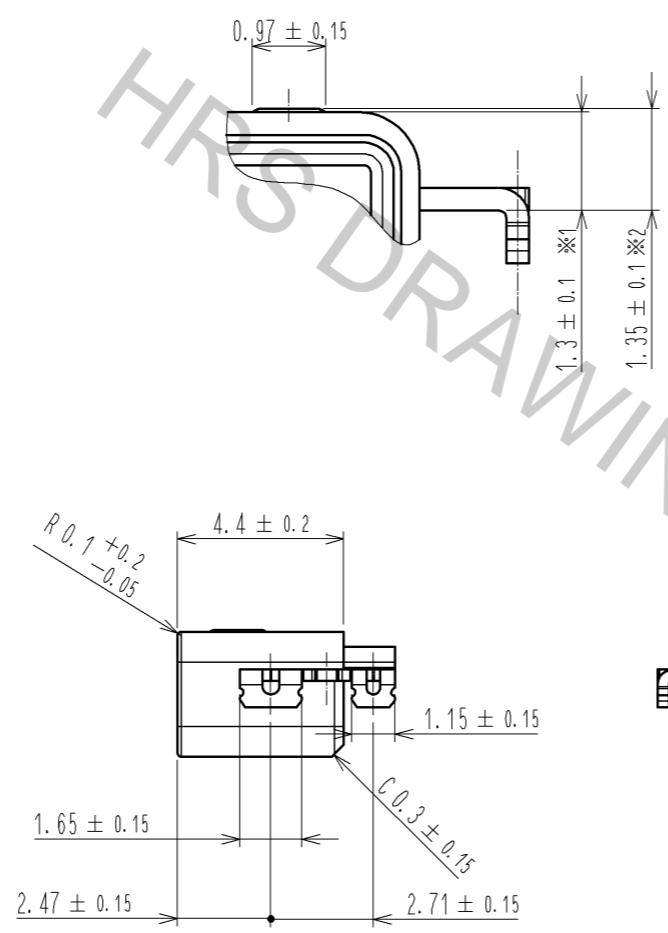
※TH/Through-Hole



NOTES.

- 1 CO-PLANARITY IS 0.08mm MAX.
- 2 PLATING  
CONTACT AREA :GOLD 0.05μm MIN OVER PALLADIUM NICKEL 0.75μm MIN.  
LEAD AREA :GOLD 0.05μm MIN.  
UNDER PLATING:NICKEL 2μm MIN.
- 3 PER REEL : 3000 pcs.
- 4. INTERFACE DIMENSIONS TO USB2.0 SPECIFICATION.
- 5. AS FOR PART 1B, THE PERFORMANCE REMAINS GOOD EVEN IF THERE IS A RUBBING WOUND BY THE ASSEMBLY PROCESS.
- 6 CODE CONFIGURATION IS SHOWN IN FIG.1.

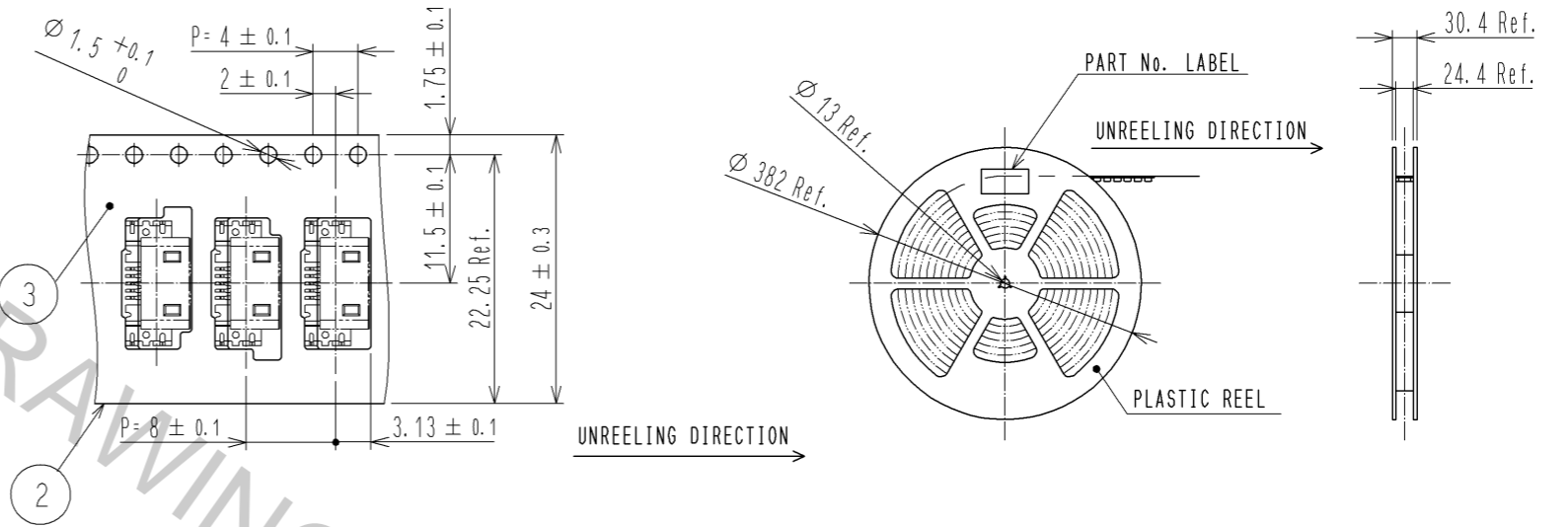
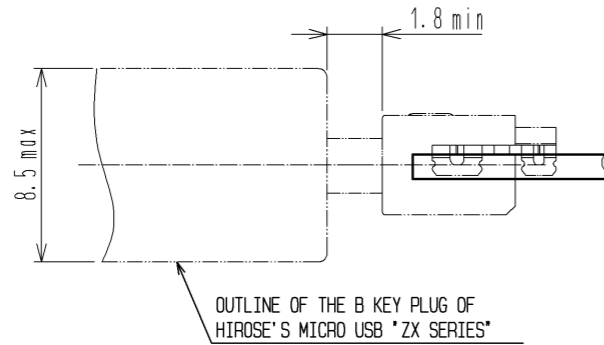
A (10 : 1)



1B	STAINLESS-STEEL	GOLD 0.01μm MIN. (SELECTIVE MATING AND SOLDERING AREA) LUBRICANT						
1A	BRASS		2	3	PE	TOP COVER TAPE		
1	LCP	BLACK	UL94V-0	2	PS	EMBOSSED CARRIER TAPE		
NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH . REMARKS		
UNITS	mm	SCALE	5 : 1	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
APPROVED : RI. TAKAYASU		13.03.07		DRAWING NO.		EDC3-127834-03		
CHECKED : NM. NISHIMATSU		13.03.07		PART NO.		ZX62WMD2-B-5PC		
DESIGNED : KO. KAWAMURA		13.03.07		CODE NO.		CL242-0073-2-00		
DRAWN : KG. OKITA		13.03.07						

MATED WITH CORRESPONDING PLUG(4:1)

3 DRAWING FOR PACKING(FREE)



6 FIG. 1. CODE CONFIGURATION FOR 4 DIGITS

Year		Month		Day						Line No.	
Year	Symbol	Month	Symbol	Day	Symbol	Day	Symbol	Day	Symbol	Line No.	Symbol
2011	1	Jan.	A	1	1	11	B	21	M	1	A
2012	2	Feb.	B	2	2	12	C	22	N	2	B
2013	3	Mar.	C	3	3	13	D	23	P	3	C
2014	4	Apr.	D	4	4	14	E	24	Q	4	D
2015	5	May.	E	5	5	15	F	25	R	5	E
2016	6	Jun.	F	6	6	16	G	26	S	6	F
2017	7	Jul.	G	7	7	17	H	27	T	7	G
2018	8	Aug.	H	8	8	18	J	28	U	8	H
2019	9	Sep.	I	9	9	19	K	29	V	9	I
2020	0	Oct.	J	10	A	20	L	30	W	10	J
		Nov.	K					31	X		
		Dec.	L								

<b>HRS</b>	DRAWING NO.	EDC3-127834-03
	PART NO.	ZX62WMD2-B-5PC
	CODE NO.	CL242-0073-2-00
		$\triangle$ 2/2